



復旦大學



# Directed Self-Assembly for Sub-10nm Fabrication

熊诗圣

@IWAPS 2018.10.19



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# 内容 Outline

1

Background 背景

2

Directed Self-Assembly

A

How does it work?

B

A downscaling story

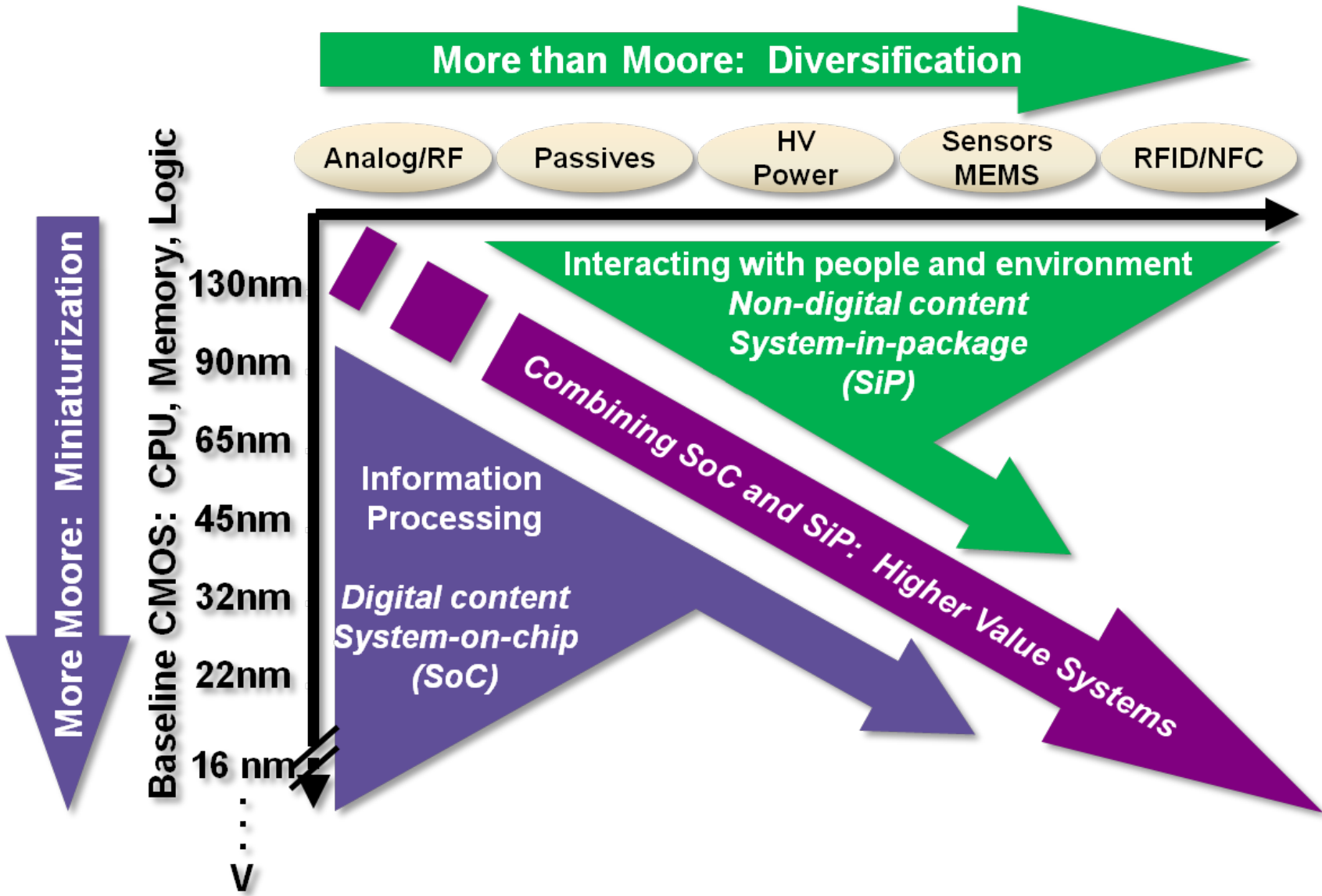
C

DSA Applications

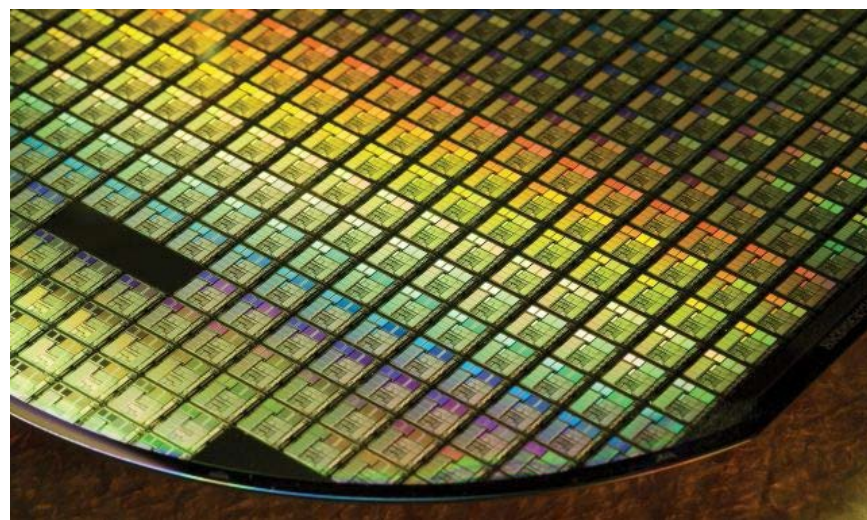
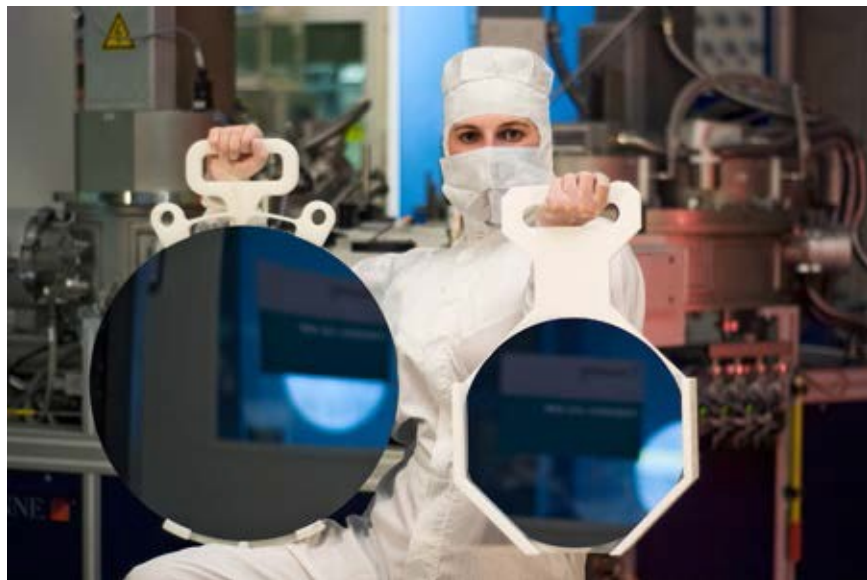
3

Summary 小结

# Extending Moore's Law



# 继续推进摩尔定律 More Moore



**7.5 Billion people in the world**

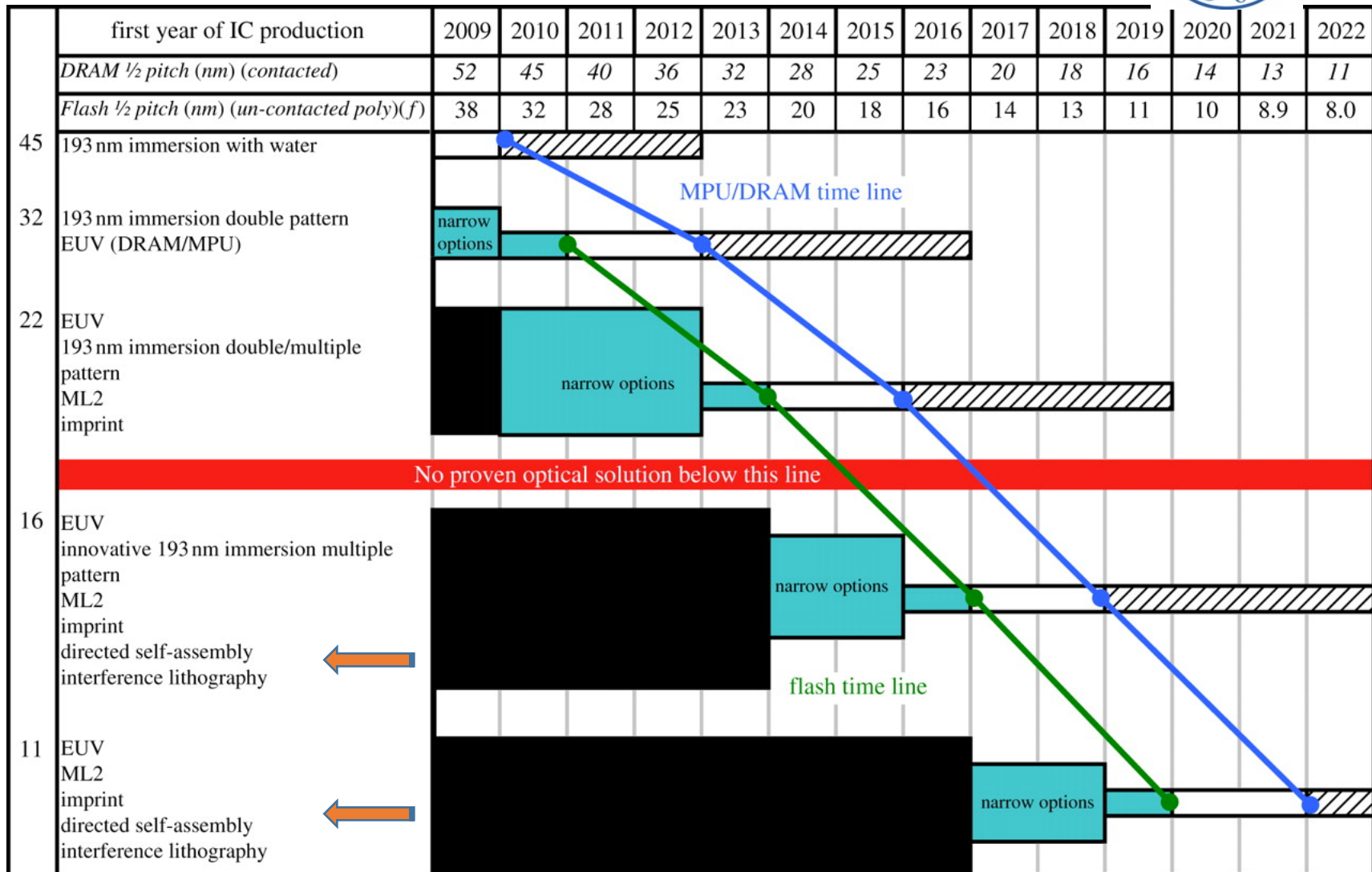


- **> 5 Billion transistors per CPU**
- **100's of CPU per wafer**

**At least 100 times more devices on one wafer than there are people in the world (百倍于人类总人数)**



# 国际半导体光刻发展路线图 (ITRS Roadmap)



the key indicates the time during which research, development and qualification/pre-production should be taking place for the solution.



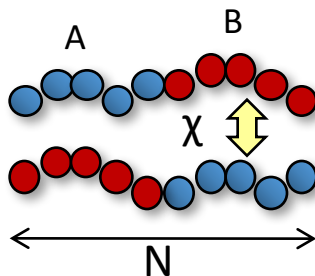
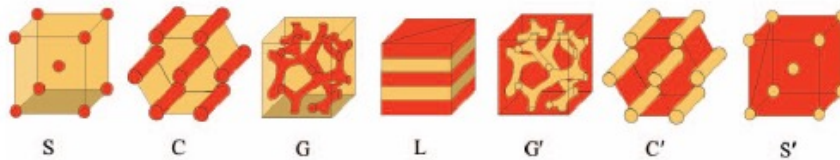
# How does DSA work 工作原理



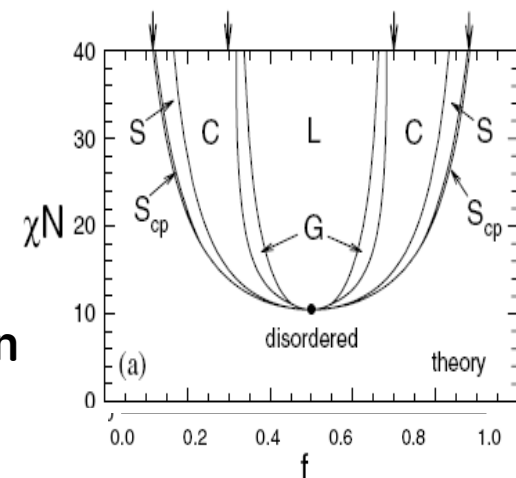
## 宏观相分离 Macrophase separation



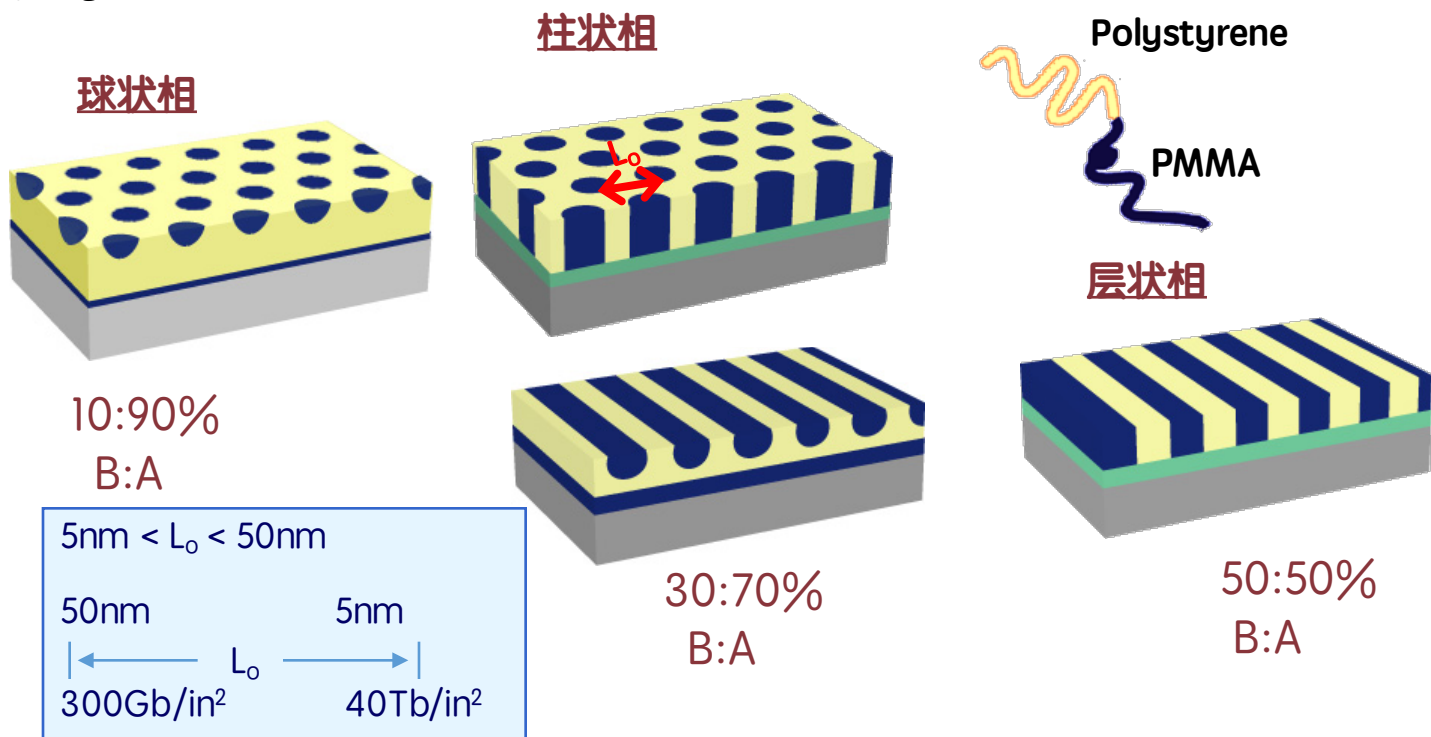
Oil + Water



## 微观相分离 Microphase separation

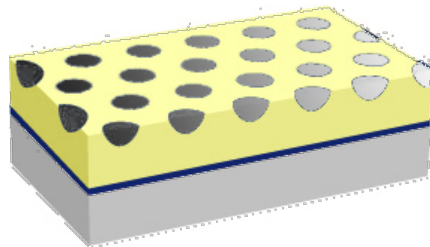


## 嵌段高分子共聚物薄膜 Block copolymer thin film



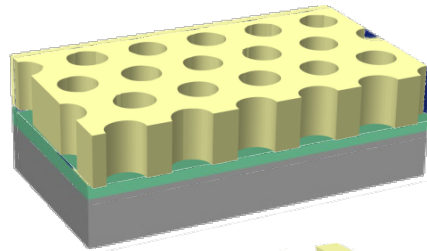
目标: 嵌段共聚物具有光刻胶的功能

球状相



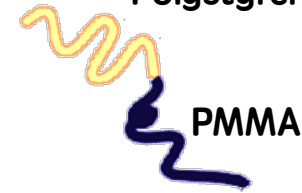
10:90%  
B:A

柱状相



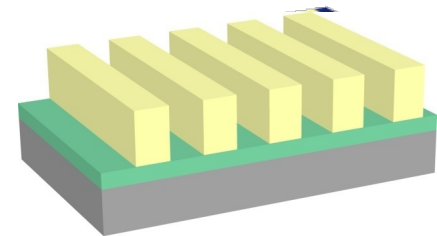
30:70%  
B:A

Polystyrene



PMMA

层状相



50:50%  
B:A

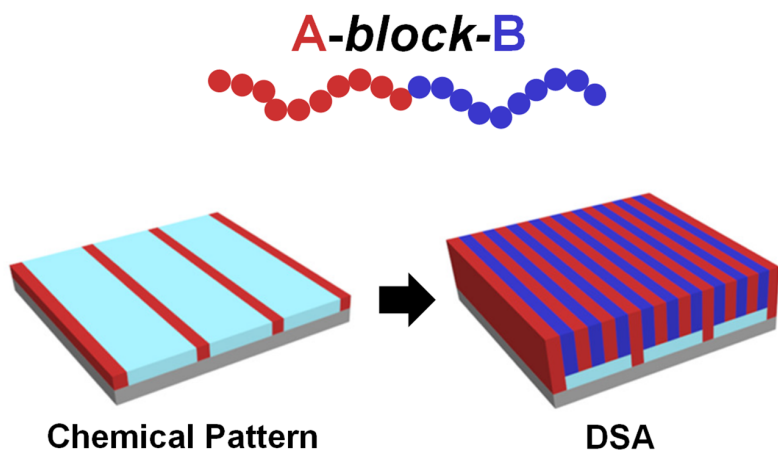
Plasma etch to remove  
one domain

目标: 嵌段共聚物具有光刻胶的功能

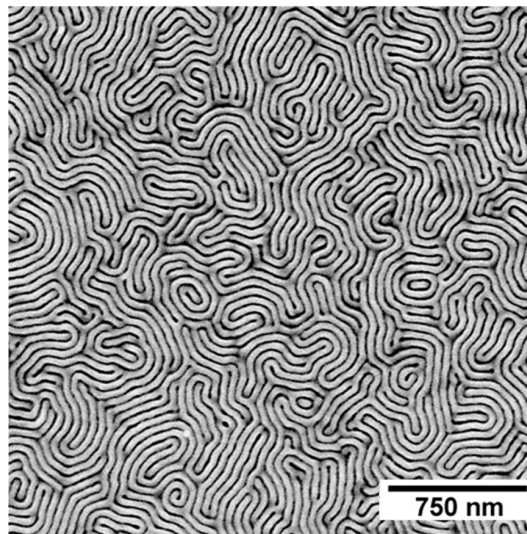


## 嵌段高分子共聚物薄膜(层状相)

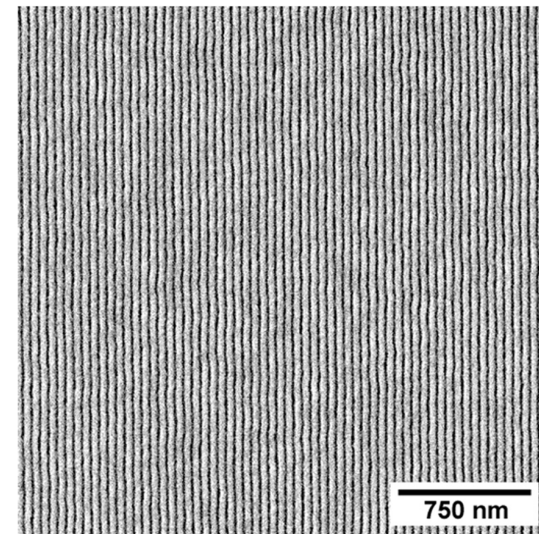
Block copolymer thin film (Lamellae)



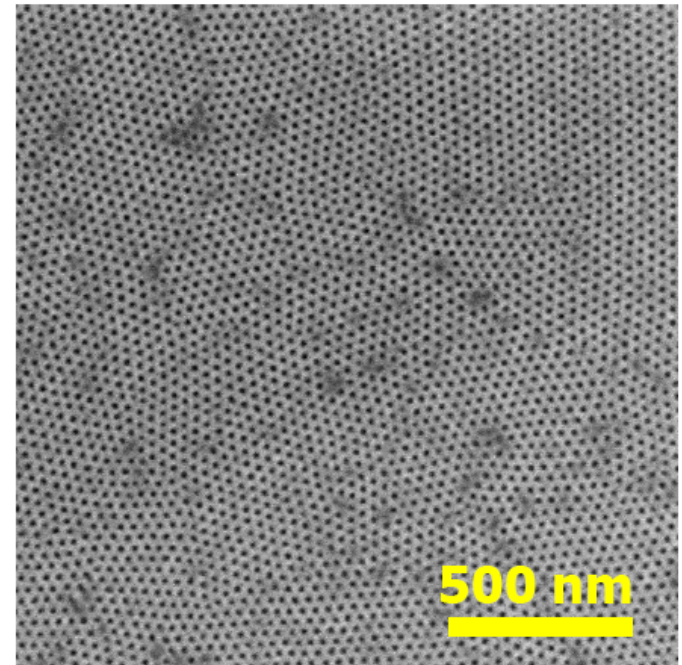
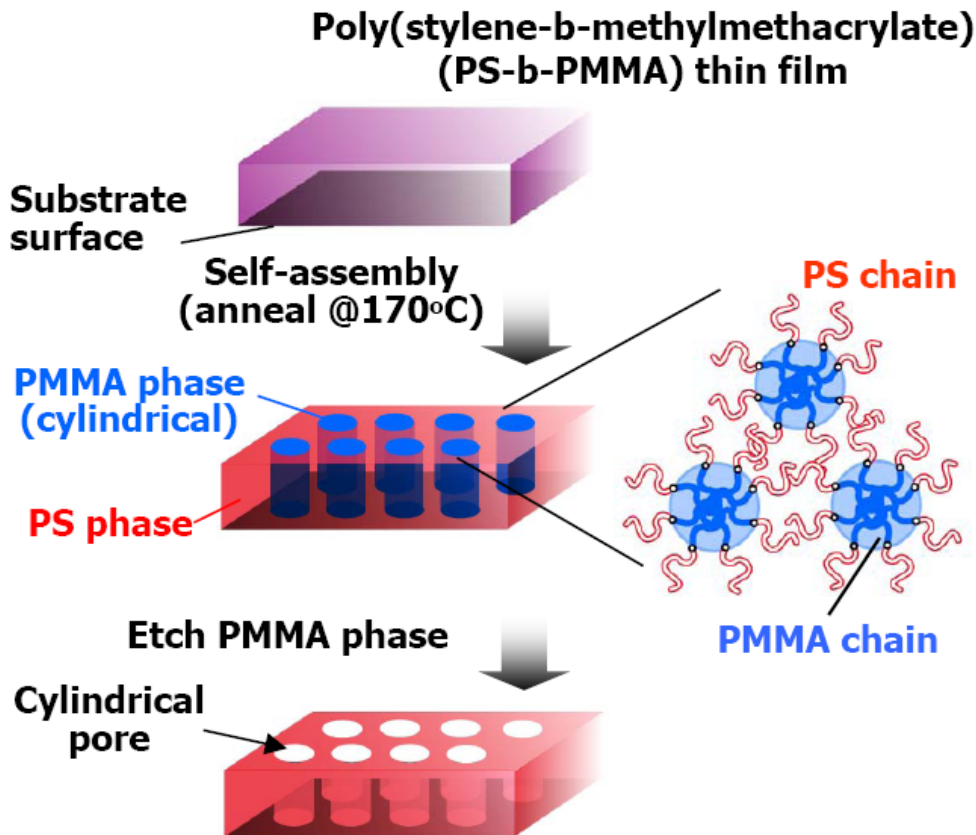
Self-Assembly



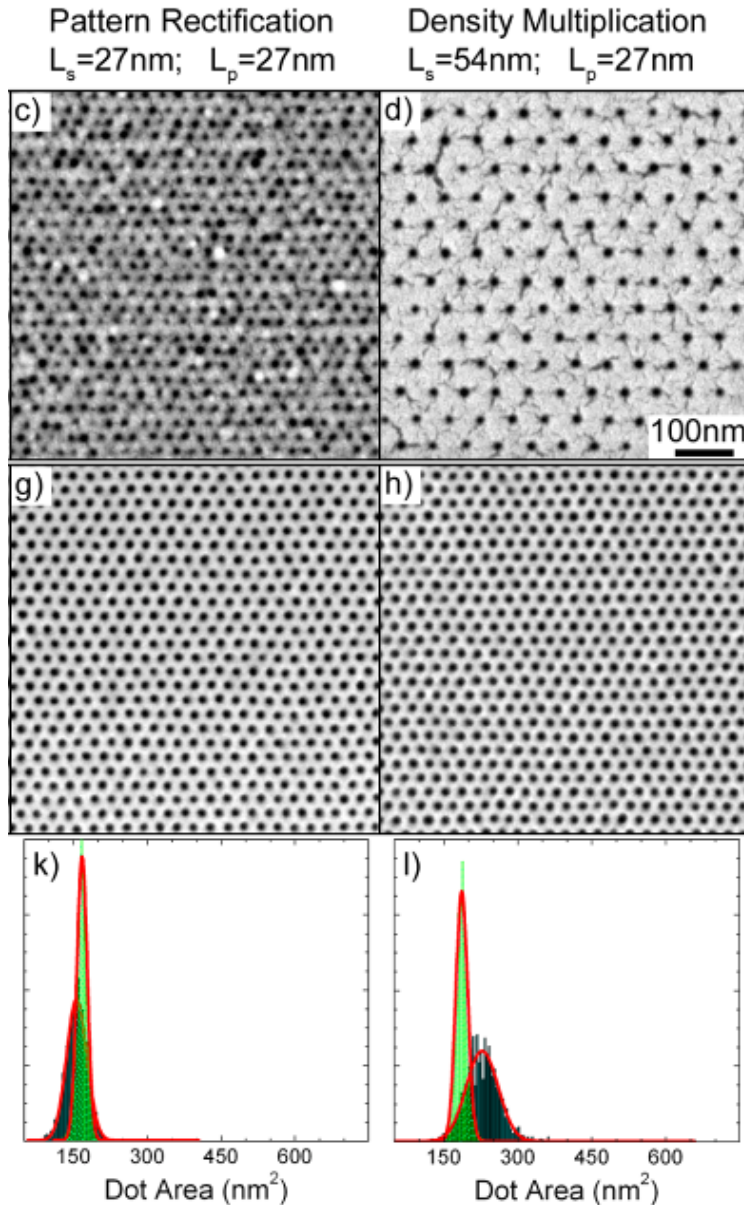
DSA on chemical pattern



热退火：导向自组装 (Nealey et. al. Nature 2003)



- Short range order: hexagonal close-pack
- Long range: disordered (without guiding)



Advantages of block copolymer directed self-assembly:

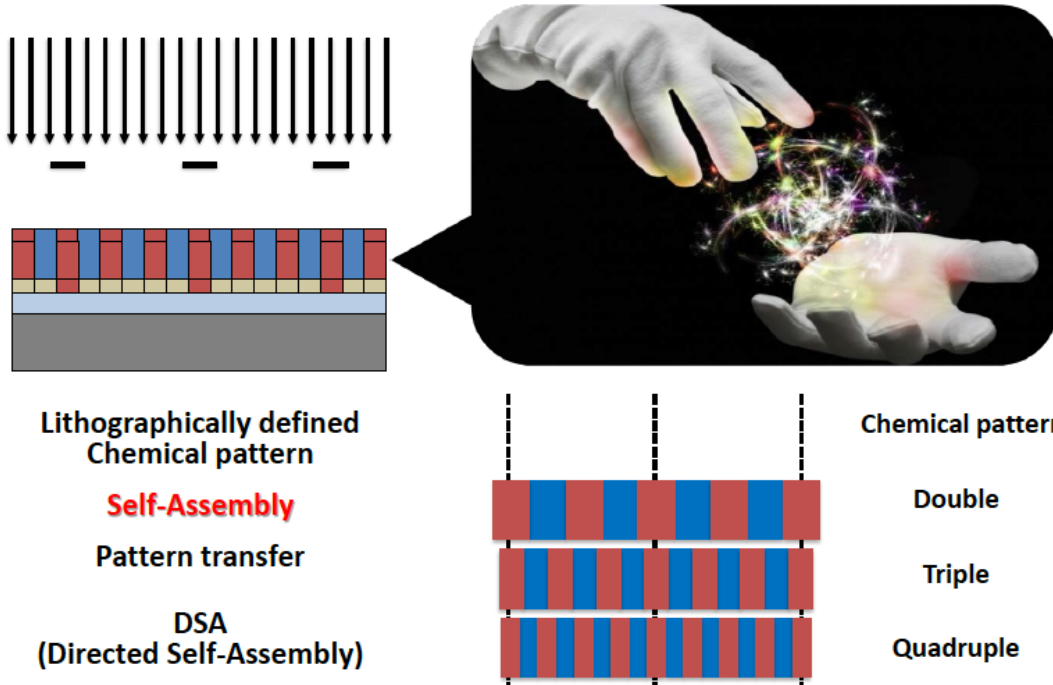
- Improved island uniformity
- Improved placement tolerance
- Density multiplication
  - beyond e-beam resolution
  - saves exposure time
- Compatible with circular tracks

(1000 Gb/in<sup>2</sup>)

R. Ruiz, H. Kang, F. A. Detcheverry, E. Dobisz, D. S. Kercher, T. R. Albrecht, J. J. de Pablo, P. F. Nealey, **Science** **2008**, 321, 936.



## Directed Self-Assembly



A downscaling  
story:

10nm,  
9nm,  
8nm,  
6nm,  
5nm,

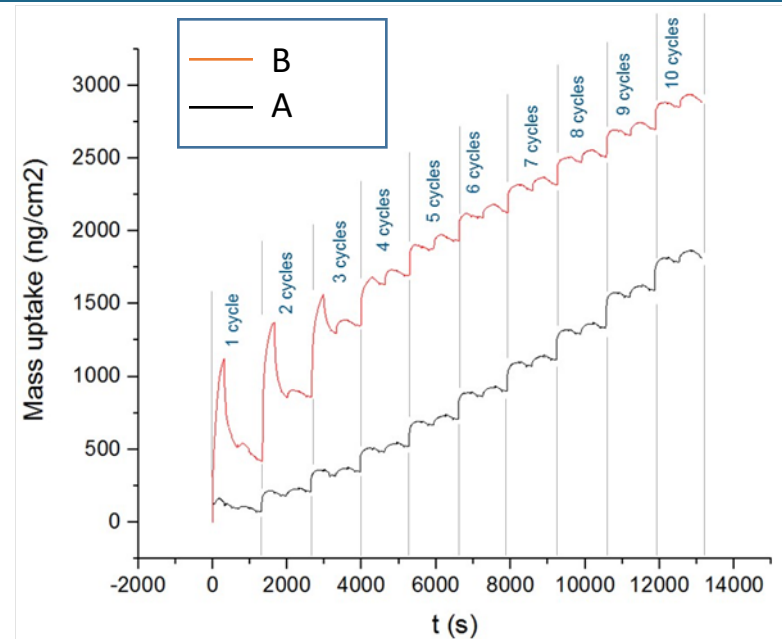
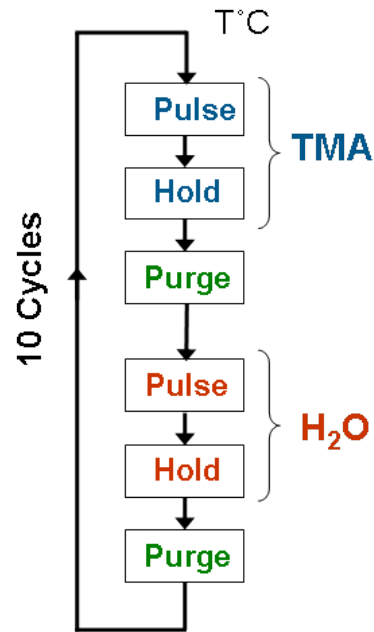
...

基于high Chi polymer，降低分子量，逐步缩小图案尺寸！



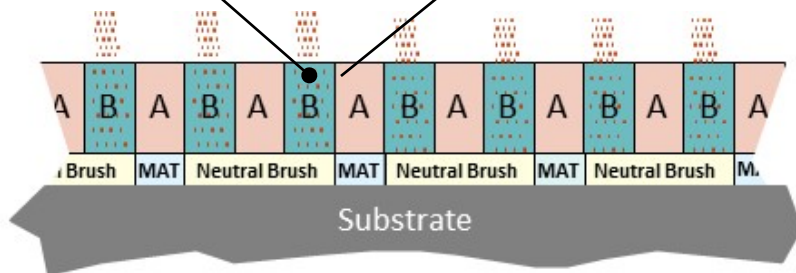


# Making a hard mask using SIS

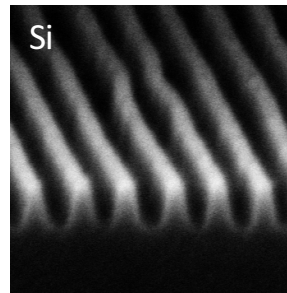
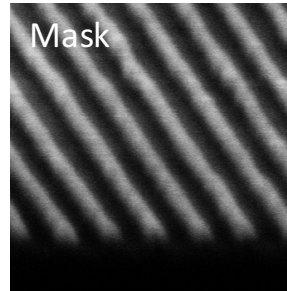


Reaction  
w/ B-block  
polymer

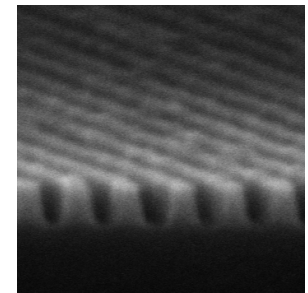
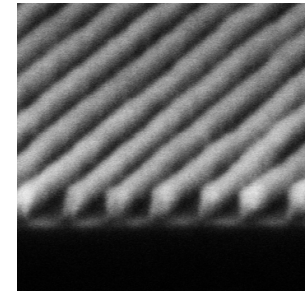
No reaction  
w/ A-block  
polymer



2cycle



3cycle





# DSA w/two different guiding strategies

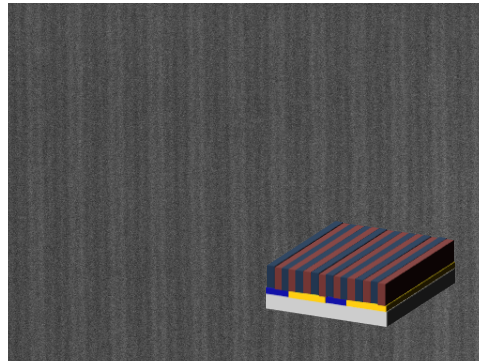
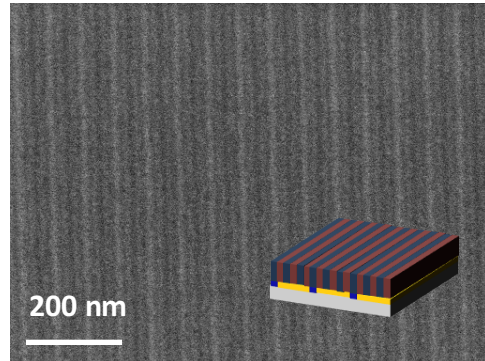
3X DSA,  $L_s=64\text{nm}$

$W \sim 0.7L_0$

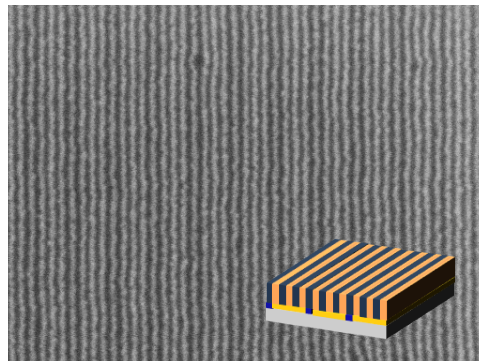
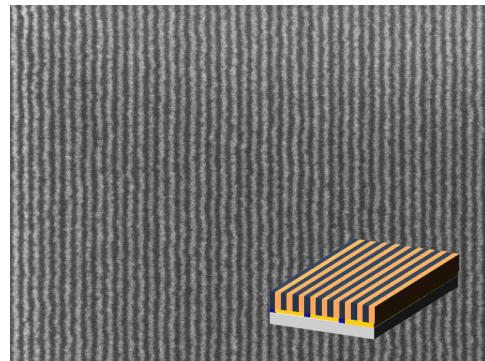
4X DSA,  $L_s=85\text{nm}$

$W \sim 1.5L_0$

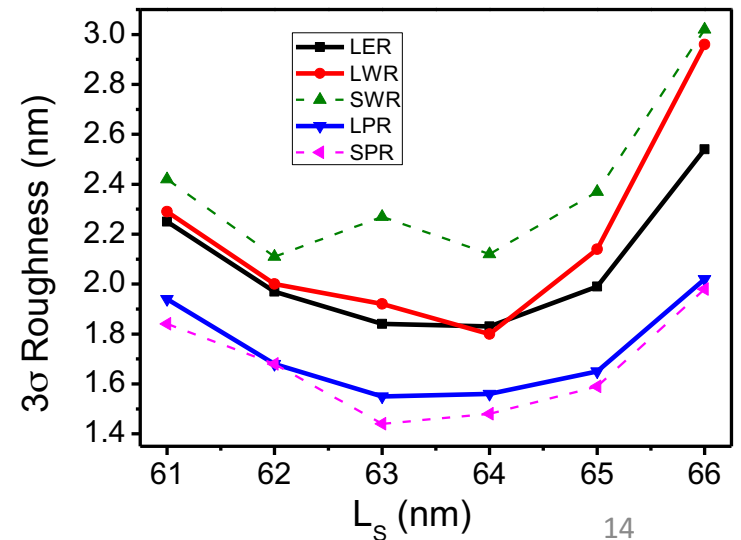
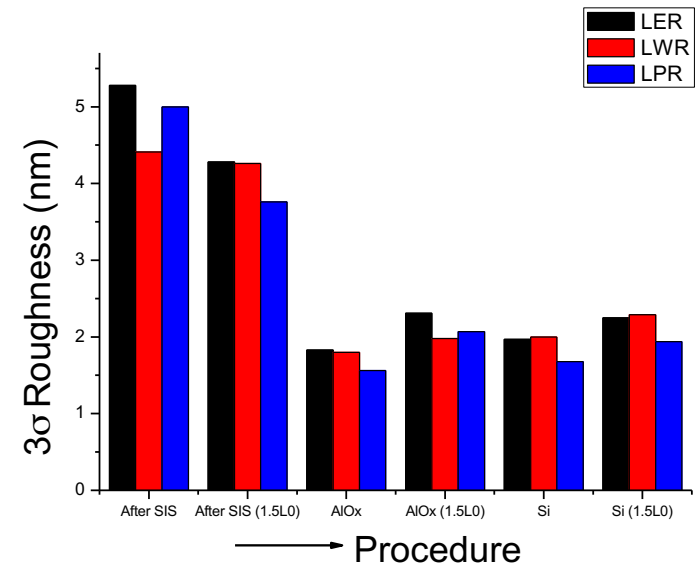
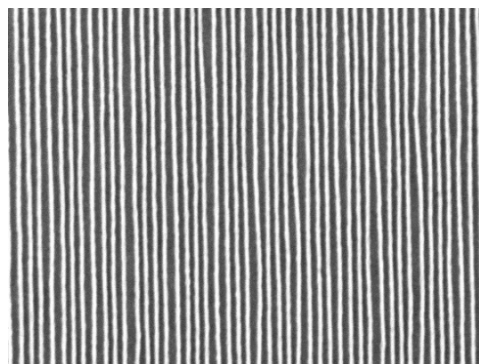
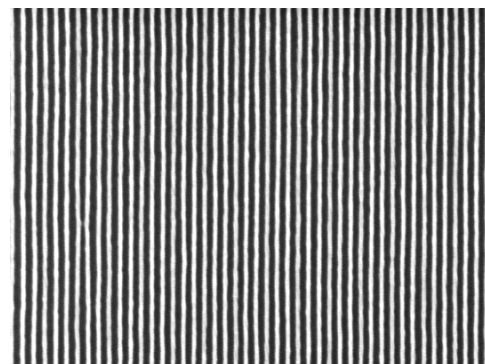
Polymer



After SIS



AlOx



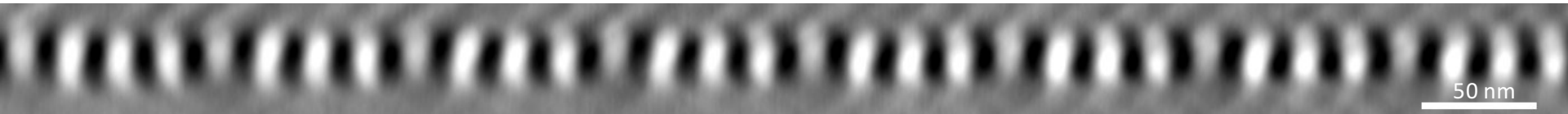




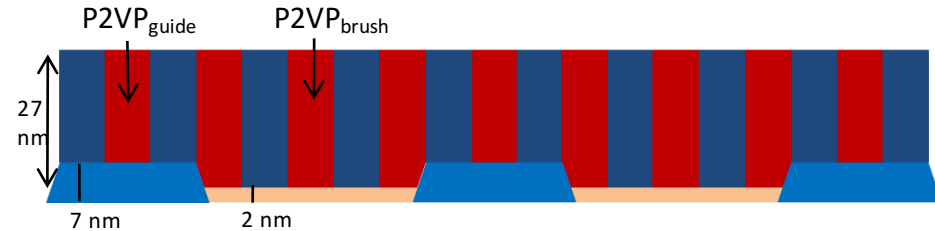
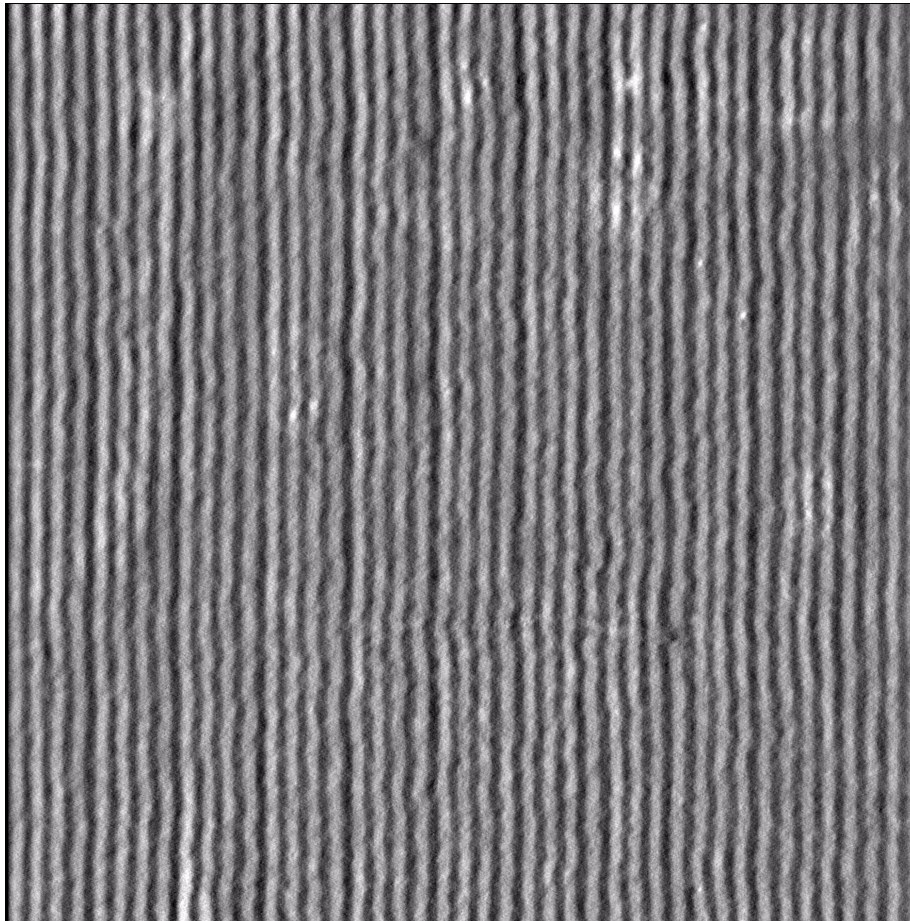
# 3D characterization by TEM tomography

$L_0=21.3$  nm, 4X density multiplication,  $W=1.5L_0$ , back filled with short PS brush

Averaged cross section:



Reconstructed structure- movie:



Averaged cross section analysis:

- $P2VP_{guide}$  lamellae are  $\sim 5$  nm shorter than  $P2VP_{brush}$ , in good agreement with the height difference in the chemical pattern.
- FWHM of  $P2VP_{brush}$  width= 11.5 nm  
FWHM of  $P2VP_{guide}$  width= 12.5 nm

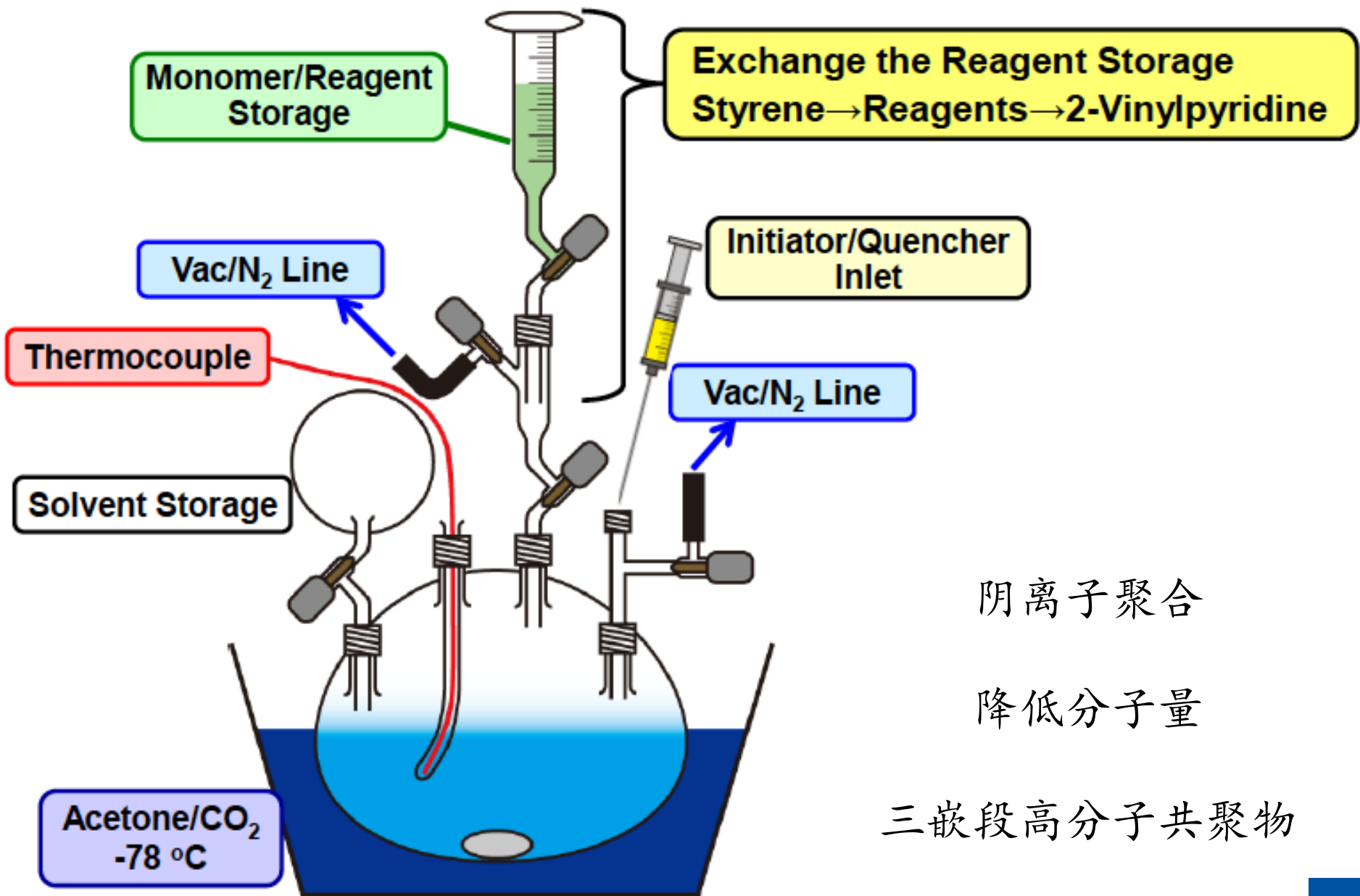
This indicates the LER of  $P2VP_{guide}$  is larger than  $P2VP_{brush}$ . Analysis of the entire 3D structure is currently conducted.

**1 Micron**  
**50 lines and 50 spaces**





# Polymerization System: Shlenk System with Inert Gas ( $N_2$ )



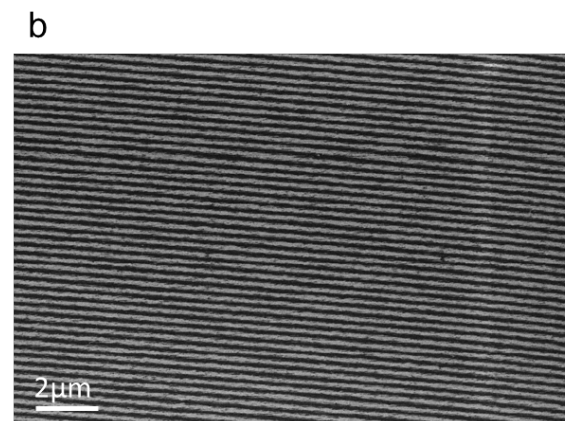
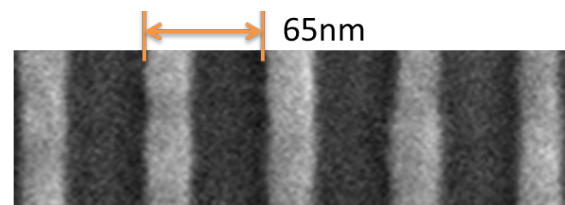
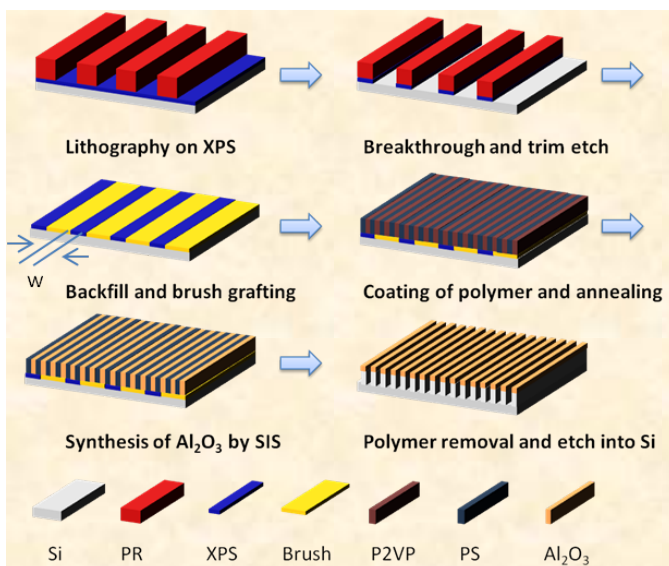
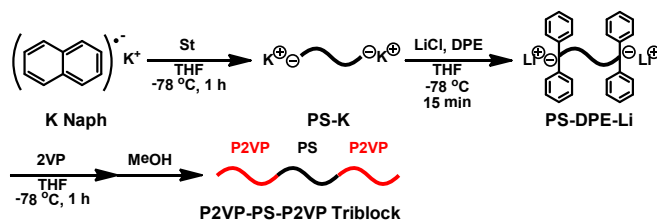
阴离子聚合

降低分子量

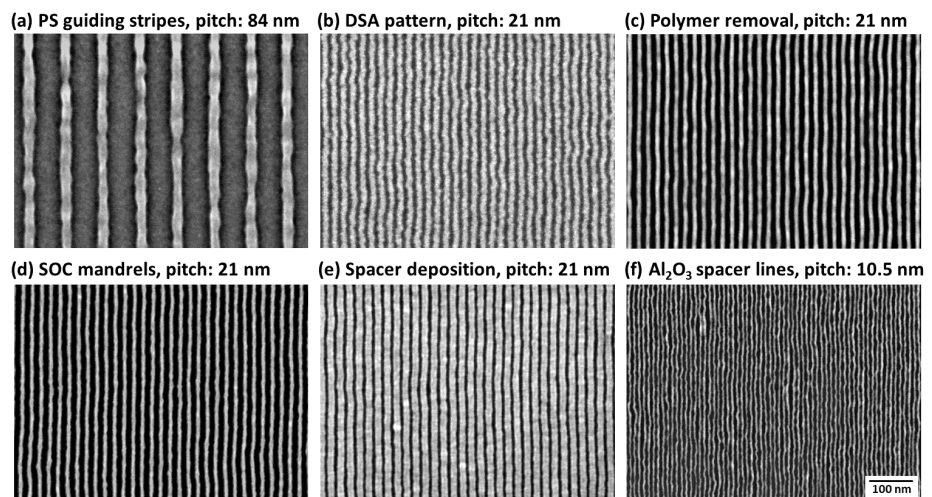
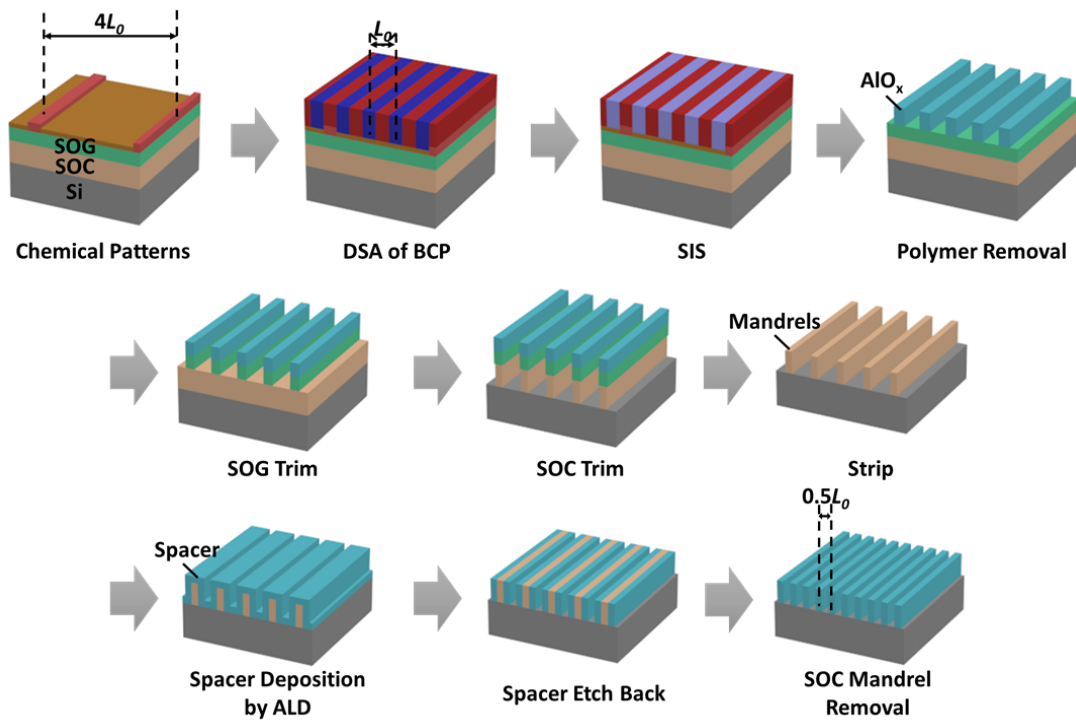
三嵌段高分子共聚物

# Directed Self-Assembly of Triblock Copolymer on Chemical Patterns for Sub-10-nm Nanofabrication *via* Solvent Annealing

Shisheng Xiong,<sup>†</sup> Lei Wan,<sup>‡</sup> Yoshihito Ishida,<sup>†,§</sup> Yves-Andre Chapuis,<sup>‡,⊥</sup> Gordon S. W. Craig,<sup>†</sup> Ricardo Ruiz,<sup>‡</sup> and Paul F. Nealey<sup>\*,†</sup>

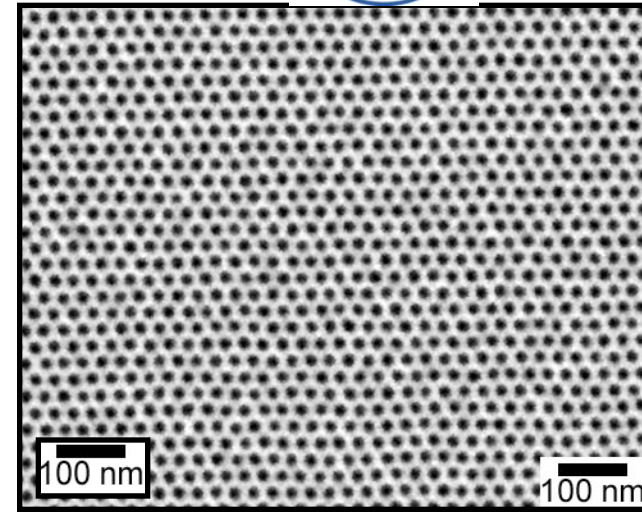
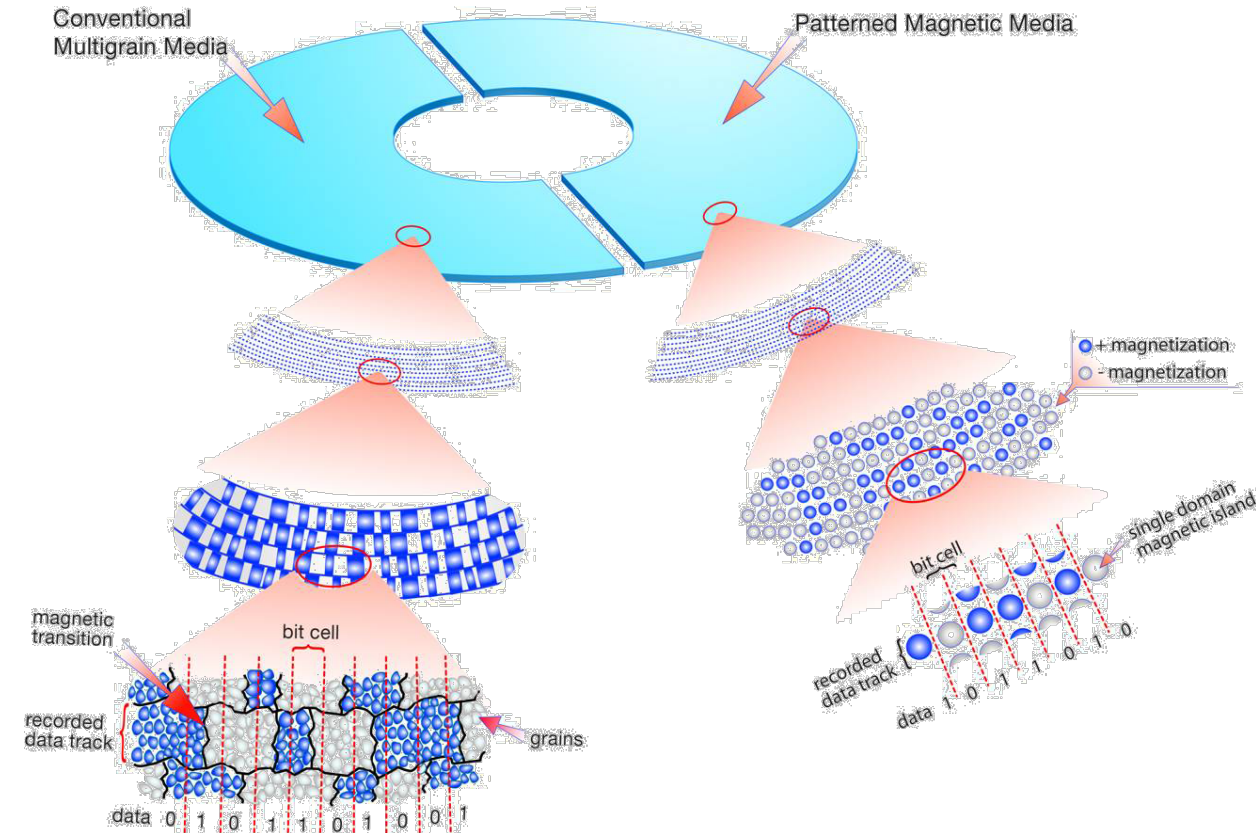


# DSA+SADP for 5nm lithography!



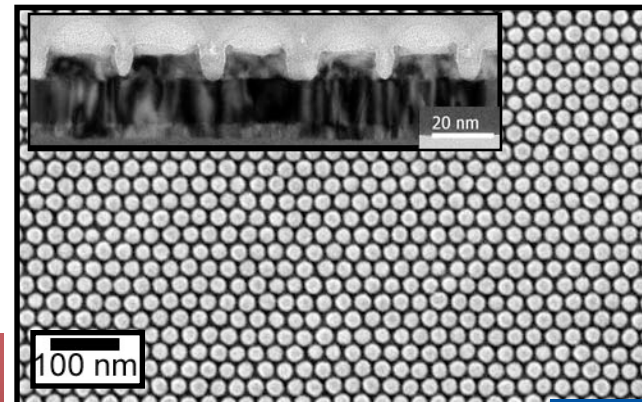


# Bit Patterned Media via DSA (w/WD)



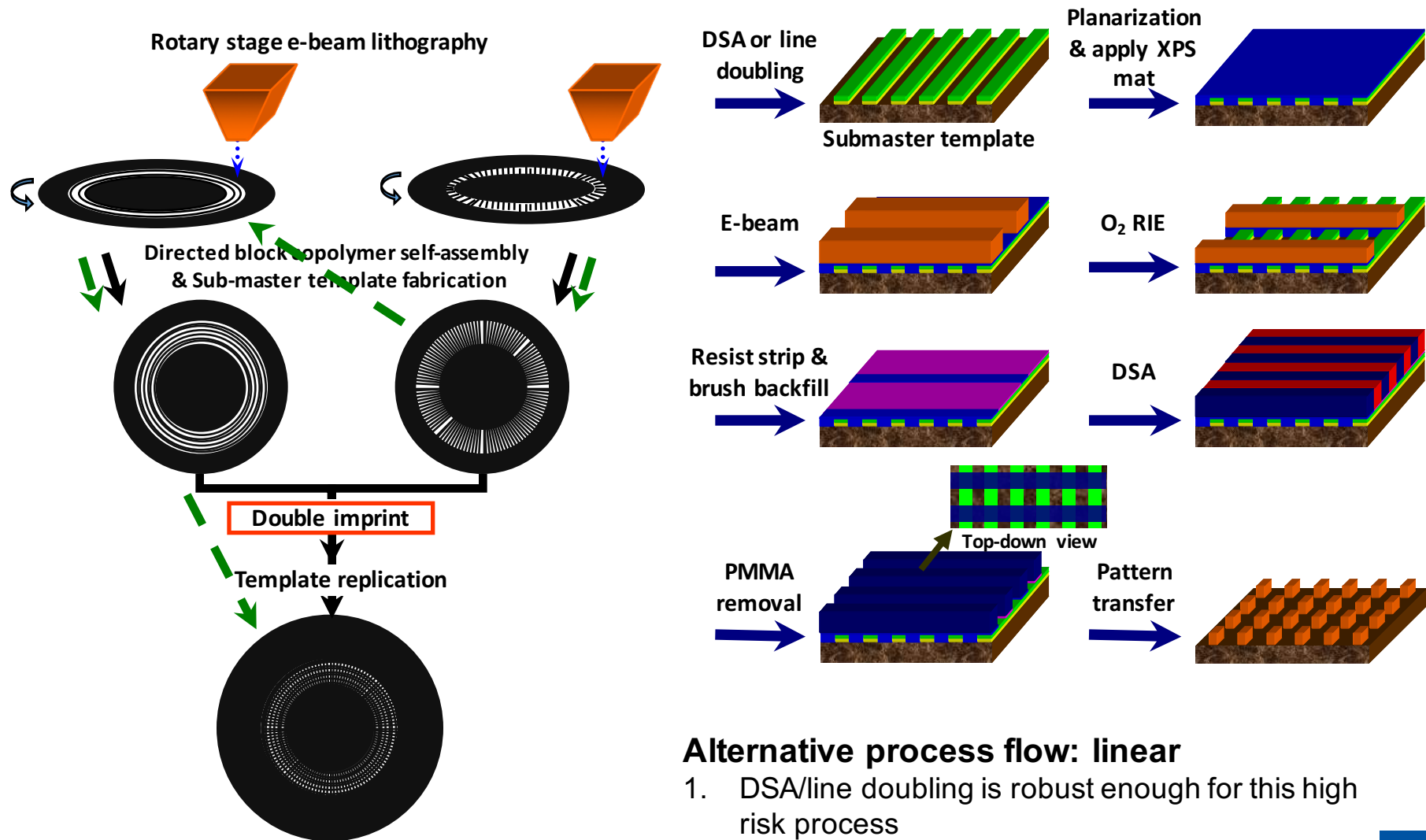
BLOCK COPOLYMER  
嵌段高分子自组装图案

FINISHED MAG ISLANDS 磁介质图案



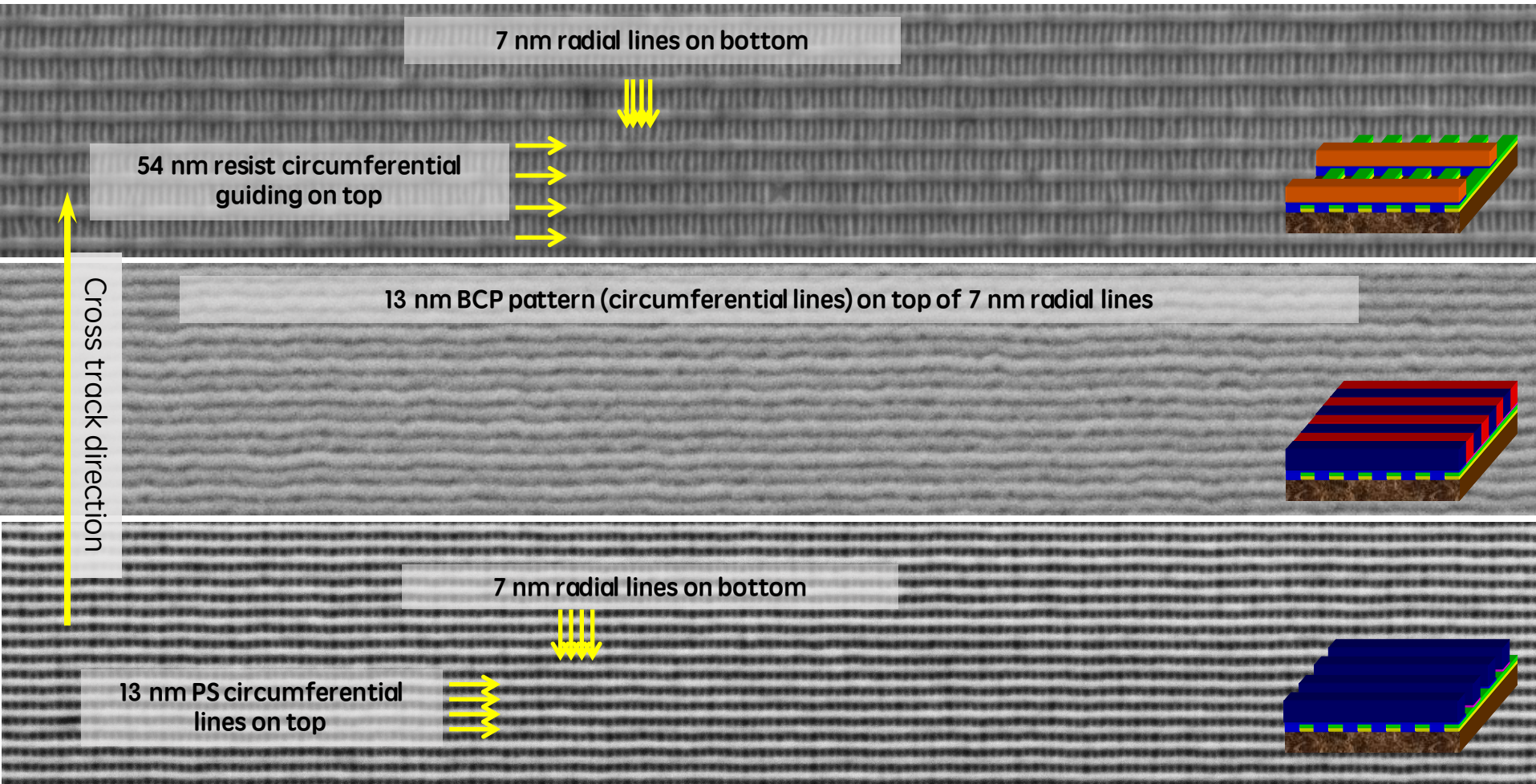
The semiconductor industry will not provide a lithography solution in time for patterned media





## Alternative process flow: linear

1. DSA/line doubling is robust enough for this high risk process
2. Needs alignment in e-beam tool

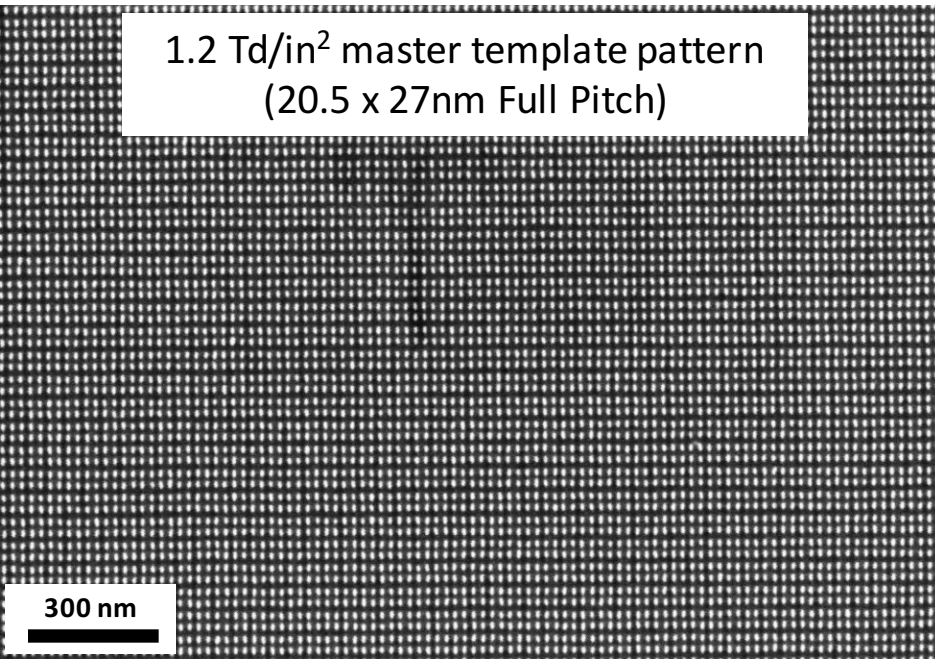




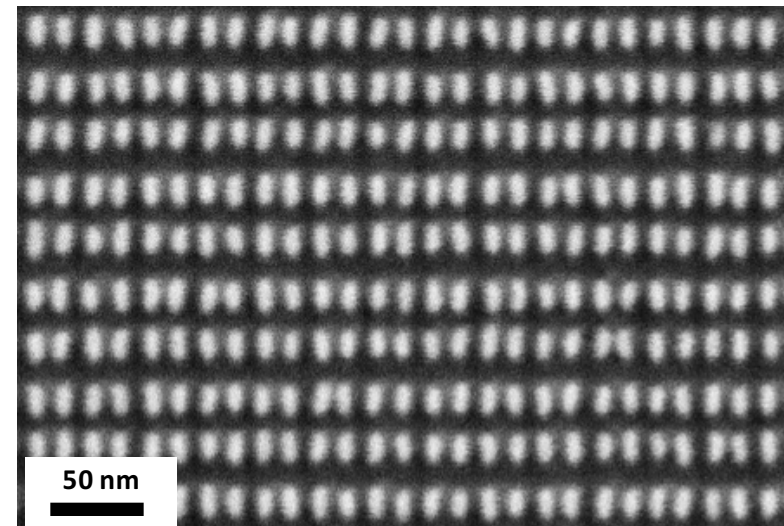
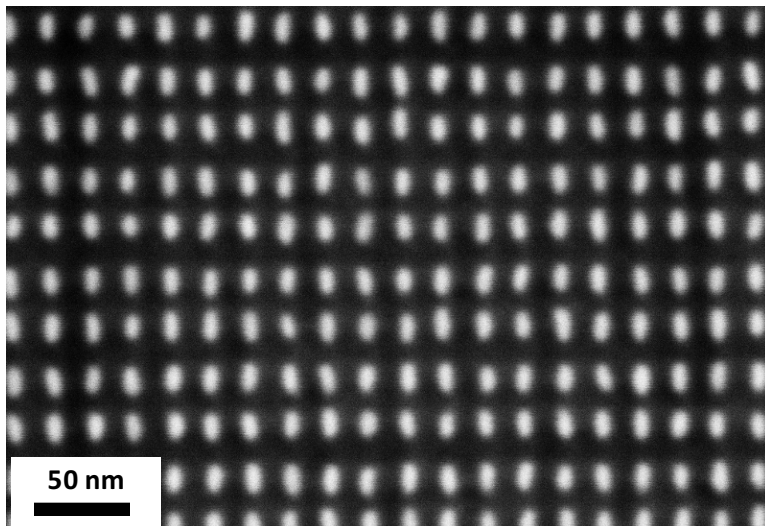
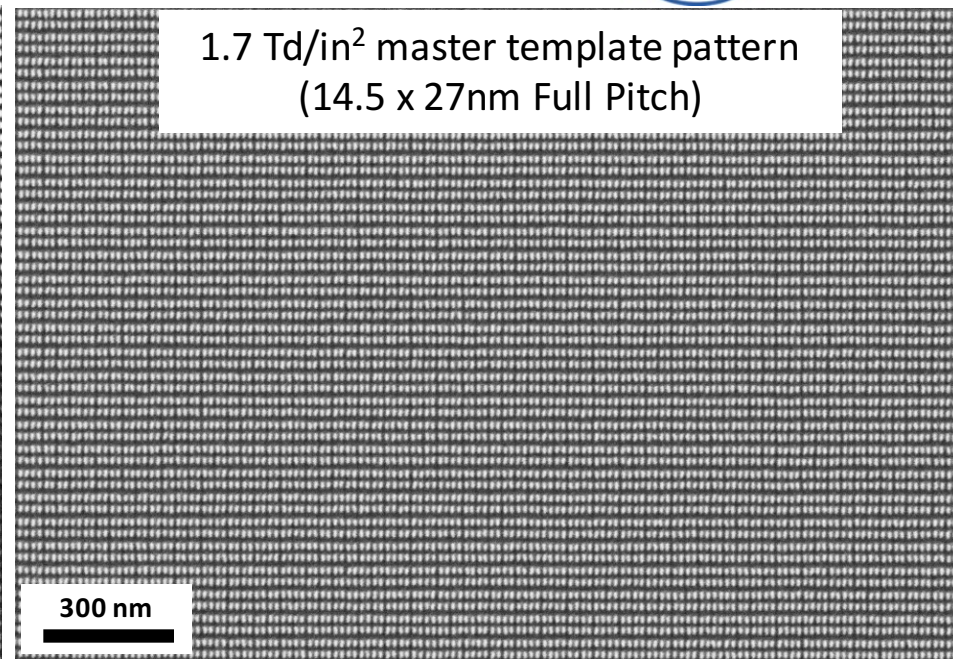
# Bit Patterned Media via DSA



1.2 Td/in<sup>2</sup> master template pattern  
(20.5 x 27nm Full Pitch)

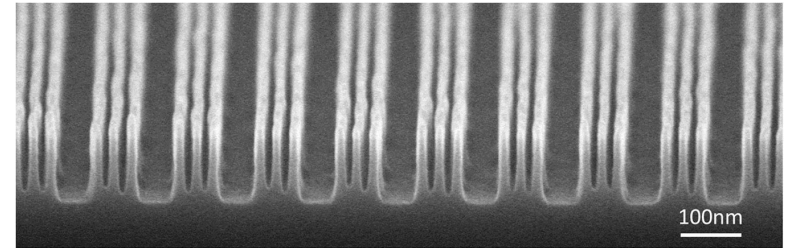


1.7 Td/in<sup>2</sup> master template pattern  
(14.5 x 27nm Full Pitch)

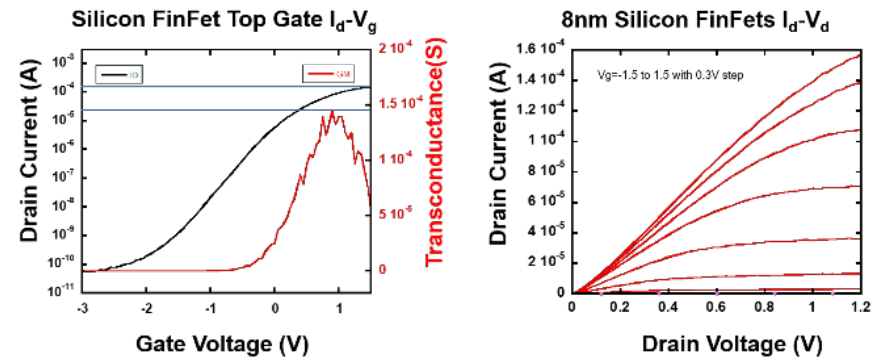
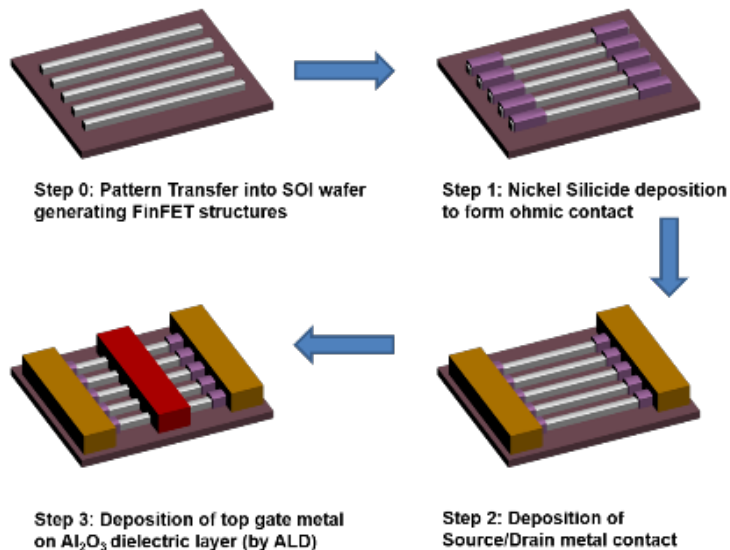




## ❖ 微纳电子器件



FinFET 鳍状场效应晶体管



开关比 $>10^6$

nature  
nanotechnology

ARTICLES

PUBLISHED ONLINE: 27 MARCH 2017 | DOI: 10.1038/NNANO.2017.34

## Sub-10-nm patterning via directed self-assembly of block copolymer films with a vapour-phase deposited topcoat

Hyo Seon Suh<sup>1,2†</sup>, Do Han Kim<sup>2†</sup>, Priya Moni<sup>3</sup>, Shisheng Xiong<sup>1,2</sup>, Leonidas E. Ocola<sup>4</sup>, Nestor J. Zaluzec<sup>5</sup>, Karen K. Gleason<sup>3\*</sup> and Paul F. Nealey<sup>1,2\*</sup>

ACS Macro Letters

Letter

pubs.acs.org/macromolecules

## Evolutionary Optimization of Directed Self-Assembly of Triblock Copolymers on Chemically Patterned Substrates

Gurdaman S. Khaira<sup>†</sup>, Jian Qin<sup>†</sup>, Grant P. Garner<sup>†</sup>, Shisheng Xiong<sup>†</sup>, Lei Wan<sup>‡</sup>, Ricardo Ruiz<sup>‡</sup>, Heinrich M. Jaeger<sup>‡</sup>, Paul F. Nealey<sup>‡,§</sup> and Juan J. de Pablo<sup>\*,†,||</sup>

Macromolecules

Article

pubs.acs.org/Macromolecules

## 1 The Solvent Distribution Effect on the Self-Assembly of Symmetric Triblock Copolymers during Solvent Vapor Annealing

3 Shisheng Xiong<sup>\*,†</sup>, Dongxue Li<sup>‡</sup>, Su-Mi Hur<sup>||</sup>, Gordon S. W. Craig<sup>§</sup>, Christopher G. Arges<sup>‡</sup>, Xin-Ping Qu<sup>‡</sup> and Paul F. Nealey<sup>\*,§</sup>

NANO LETTERS

Letter

pubs.acs.org/NanoLett

## InAs Nanowires Grown by Metal–Organic Vapor-Phase Epitaxy (MOVPE) Employing PS/PMMA Diblock Copolymer Nanopatterning

Yinggang Huang<sup>†</sup>, Tae Wan Kim<sup>†</sup>, Shisheng Xiong<sup>‡</sup>, Luke J. Mawst<sup>\*,†</sup>, Thomas F. Kuech<sup>‡</sup>, Paul F. Nealey<sup>‡</sup>, Yushuai Dai<sup>‡</sup>, Zihao Wang<sup>§</sup>, Wei Guo<sup>§</sup>, David Forbes<sup>§</sup>, Seth M. Hubbard<sup>§</sup> and Michael Nesidal<sup>||</sup>

ACS NANO

www.acsnano.org

## Quantitative Three-Dimensional Characterization of Block Copolymer Directed Self-Assembly on Combined Chemical and Topographical Prepatterned Templates

Tamar Segal-Peretz<sup>†,‡,§,||</sup>, Jiaying Ren<sup>†,‡,||</sup>, Shisheng Xiong<sup>†</sup>, Gurdaman Khaira<sup>†</sup>, Alec Bowen<sup>†</sup>, Leonidas E. Ocola<sup>||</sup>, Ralu Divan<sup>||</sup>, Manolis Doxastakis<sup>†</sup>, Nicola J. Ferrier<sup>†,‡</sup>, Juan de Pablo<sup>†,‡</sup> and Paul F. Nealey<sup>\*,†,§</sup>

ACS NANO

www.acsnano.org

## Directed Self-Assembly of Triblock Copolymer on Chemical Patterns for Sub-10-nm Nanofabrication via Solvent Annealing

Shisheng Xiong<sup>†</sup>, Lei Wan<sup>‡</sup>, Yoshihito Ishida<sup>†,§</sup>, Yves-Andre Chapuis<sup>†,‡</sup>, Gordon S. W. Craig<sup>†</sup>, Ricardo Ruiz<sup>‡</sup> and Paul F. Nealey<sup>\*,†</sup>

ACS NANO

www.acsnano.org

## 1 Pathways to Mesoporous Resin/Carbon Thin Films with Alternating Gyroid Morphology

3 Qi Zhang<sup>†</sup>, Fumiaki Matsuoka<sup>†</sup>, Hyo Seon Suh<sup>†,§</sup>, Peter A. Beaucage<sup>†</sup>, Shisheng Xiong<sup>†,§</sup>, Detlef-M. Smilgies<sup>||</sup>, Kwan Wee Tan<sup>†,‡</sup>, Jörg G. Werner<sup>†</sup>, Paul F. Nealey<sup>†,§</sup> and Ulrich B. Wiesner<sup>\*,†</sup>

NANO LETTERS

Letter

pubs.acs.org/NanoLett

## Directed Self-Assembly of Polystyrene-*b*-poly(propylene carbonate) on Chemical Patterns via Thermal Annealing for Next Generation Lithography

Guan-Wen Yang<sup>†</sup>, Guang-Peng Wu<sup>\*,†</sup>, Xuanxuan Chen<sup>†</sup>, Shisheng Xiong<sup>†,||</sup>, Christopher G. Arges<sup>‡</sup>, Shengxiang Ji<sup>‡</sup>, Paul F. Nealey<sup>\*,†,||</sup>, Xiao-Bing Lu<sup>‡</sup>, Donald J. Darensbourg<sup>‡</sup> and Zhi-Kang Xu<sup>\*,†</sup>



復旦大學



**Thank you!**

**FUDAN University**  
**[sxiong@fudan.edu.cn](mailto:sxiong@fudan.edu.cn)**  
**(86) 135-2424-7090**

**Acknowledgement to Uchicago  
and Western digital company**

**復旦大學信息科學與工程學院**